

**RELIABILITY FAILURE RATE SUMMARY**

Search Results														
PR_Tech:	Early Life Failure Rate	MTBF / FIT		Early Life Failure Rate Supporting Data				MTBF / FIT Supporting Data						
	ELFR-DPPM	MTBF	FIT	Confidence Level (%)	Test Temp. (°C)	Sample Size	Number of Failures	Usage Temp. (°C)	Confidence Level (%)	Activation Energy (eV)	Test Temp. (°C)	Test Duration (hrs)	Sample Size	Number of Failures
CSD95372A/BQ5M in FET_NCH_LV_Gen2.1	-	3.45E+08	2.9	-	-	-	-	55	60	0.7	125	1000	8259	0

- <sup>1</sup> Assuming an ambient temperature of 55°C
- <sup>2</sup> Chi-squared 60% estimations used to calculate the failure rate
- <sup>3</sup> Equivalent unit hours (EUH)
- <sup>4</sup> Thermal acceleration factor is calculated from the Arrhenius equation

$$AF = \exp [(Ea/k) \times (1/Tu - 1/Ta)]$$

where:

AF = acceleration factor

Ea = apparent activation energy in electron volts (eV)

K = Boltzmann's constant (8.617 x 10<sup>-5</sup> electron volts/°Kelvin)

Tu = junction temperature at normal use conditions in degrees Kelvin

Ta = junction temperature at accelerated conditions in degrees Kelvin

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